

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-26 (Canceled)

27. (Currently Amended) A circuit structure, comprising:
an integrated circuit package;
at least one signal pin;
a circuit board; and
a support member for supporting the at least one signal pin, the at least one signal pin and the support member being disposed between the integrated circuit package and the circuit board, the at least one signal pin electrically and physically interconnecting the circuit board and the integrated circuit package, wherein the support member is a two or more pin stanchion, the stanchion being a vertically oriented member of insulating material which has holes allowing the passage of the at least one signal pin in a vertical orientation with respect to a plane of major extension of the circuit board, the support member being placed only at the corners of the integrated circuit package.

28. (Canceled)

29. (Canceled)

30. (Currently Amended) The circuit structure of Claim 27 28, wherein the support member entirely encloses an area.

31. (Currently Amended) A circuit structure, comprising:
an integrated circuit package;
at least one signal pin;
a circuit board; and
a support member for supporting the at least one signal pin, the at least one
signal pin and the support member being disposed between the integrated circuit
package and the circuit board, the at least one signal pin electrically and physically
interconnecting the circuit board and the integrated circuit package, wherein the support
member entirely encloses an area. ~~The circuit structure of Claim 30, further~~
~~comprising a signal pin being which~~ is unsupported by a stanchion in the area enclosed
by the support member.

32. (Original) The circuit structure of Claim 27, wherein the support member is
a layer of insulating material oriented parallel to the plane of major extension of the
circuit board, the support member having holes for allowing the passage of the signal
pins.

33. (Original) The circuit structure of Claim 32, wherein the support member
forms a permanent part of the circuit structure.

34. (Currently Amended) A circuit structure, comprising:
an integrated circuit package;
at least one signal pin;
a circuit board; and
a support member for supporting the at least one signal pin, the at least one
signal pin and the support member being disposed between the integrated circuit
package and the circuit board, the at least one signal pin electrically and physically
interconnecting the circuit board and the integrated circuit package, wherein the support
member is a layer of insulating material oriented parallel to the plane of major
extension of the circuit board, the support member having holes for allowing the

passage of the signal pins, ~~The circuit structure of Claim 32, wherein~~ the support member dissolving ~~dissolves~~ with the application of heat.

35. (Previously Amended) The circuit structure of Claim 27, wherein the at least one signal pin is cylindrical and is non-fluted.

36. (Previously Amended) The circuit structure of claim 27, wherein the at least one signal pin is fluted.

37. (Canceled)

38. (Previously Amended) The circuit structure of Claim 36, the at least one signal pin comprising a cap at one end.

39. (Currently Amended) A circuit structure, comprising:
an integrated circuit package;
at least one signal pin;
a circuit board; and
a support member for supporting the at least one signal pin, the at least one signal pin and the support member being disposed between the integrated circuit package and the circuit board, the at least one signal pin electrically and physically interconnecting the circuit board and the integrated circuit package, wherein the at least one signal pin is fluted, and ~~The circuit structure of Claim 38,~~ wherein the cap is screwed onto the at least one signal pin.

40. (Currently Amended) The circuit structure of Claim ~~39~~ 38, wherein the cap is made of a high dielectric constant material.

41. (Previously Amended) The circuit structure of Claim 40, wherein the support member is a permanent, insulating stanchion that supports the at least one signal pin.

42. (Currently Amended) The circuit structure of Claim 39 38, wherein the cap is made of conductive material.

43. (Previously Amended) The circuit structure of Claim 42, wherein the integrated circuit package has a recess and the cap adheres to the recess on the integrated circuit package through an adhesive melt.

44. (Previously Amended) The circuit structure of Claim 43, wherein the support member is a permanent, insulating stanchion that supports the at least one signal pin.

45. (Previously Amended) The circuit structure of Claim 27, wherein the at least one signal pin is fluted and is supported by the support member.

46. (Previously Added) The circuit structure of Claim 38, wherein the cap has a maximum height approximately equal to one third of the diameter of a standardized solder ball useable to connect the integrated circuit package to the circuit board.

47. (Previously Added) The circuit structure of Claim 27, wherein the integrated circuit package is a ball grid array package.

48. (Previously Added) The circuit structure of Claim 27, wherein the integrated circuit package is a pin ball grid array package.

49. (Previously Added) The circuit structure of Claim 27, wherein the at least one signal pin is attached to the integrated circuit package with metallic solder.

50. (Previously Added) The circuit structure of Claim 27, wherein the at least one signal pin is attached to the integrated circuit package with conductive adhesive.

51. (Currently Amended) A circuit structure, comprising:
an integrated circuit package;

at least one signal pin;
a circuit board; and
a support member for supporting the at least one signal pin, the at least one signal pin and the support member being disposed between the integrated circuit package and the circuit board, the at least one signal pin electrically and physically interconnecting the circuit board and the integrated circuit package. ~~The circuit structure of Claim 27,~~ wherein the support member is a dissolving type of membrane.

52. (Previously Added) The circuit structure of Claim 51, wherein the dissolving type of membrane dissolves with the application of heat.

53. (Previously Added) The circuit structure of Claim 51, wherein the dissolving type of membrane dissolves in water.

54. (Previously Added) The circuit structure of Claim 32, wherein the support member is capable of being washed away with water.

55. (Currently Amended) A circuit structure, comprising:
an integrated circuit package;
a circuit board; and
at least one fluted signal pin being disposed between the integrated circuit package and the circuit board, the at least one fluted signal pin electrically and ~~physical~~ physically interconnecting the circuit board and the integrated circuit package, the at least one fluted signal pin comprising a cap at one end.

56. (Canceled)

57. (Currently Amended) The circuit structure of Claim 55 ~~56~~, wherein the cap is screwed onto the one end of the at least one fluted signal pin.

58. (Currently Amended) The circuit structure of Claim 55 ~~56~~, wherein the cap is made of a high dielectric constant material.